

Daric Security MCU



CR7SE01

ARM M7 MCU and integrated Secure Element TSMC 22nm ULL Process Node

Data Sheet – Advanced Information

Features

- Powerful ARM M7 CPU
 - o 800MHz CPU/400MHz AXI
 - o FPU, double precision
 - o MPU, 16 entries
 - o Icache 16kB, Dcache 16kB
 - o iTCM 256kB, dTCM 64kB
- RISC-V CPU
 - o 400MHz CPU
 - o MMU
 - o Icache 16kB, Dcache 16kB
- Large high-speed memory system
 - o 4MByte embedded NVM
 - RRAM robust against physical attack, aging, & environment
 - 2MBvte main SRAM
 - Separate buffer RAM for I/O
 - o 2x QSPI for off-chip memory
- Flexible I/O set
 - o I2S, I2C
 - o O/SPIM, SPIS
 - o Camera IF
 - o SD Host
 - o UART
 - o USB2.0
 - QSPI Flash controller
 - Aux ADC/PWM DAC
 - GPIO/GPINT
- Embedded Cryptographic Engine
 - o Isolated from CPU bus
 - Asymmetric cryptography
 - ECDSA, Schnorr, EdDSA and ECDH (secp256k1, P-256/384, ed25519, Curve25519)
 - RSA, up to 8192 bit
 - Symmetric cryptography
 - AES
 - Homomorphic Encryption



- Paillier cryptosystem
- Hashes
 - SHA2, SHA3/Keccak, RIPEMD160, BLAKE2/3
- Authentication codes
 - HMAC 256/512
- High Speed TRNG
- Monotonic counters
- Logical security
 - Boot / lifecycle protection
 - Test mode sealing / debug mode sealing
 - o Crypto engine isolated from CPU
 - Detailed memory protection/privilege
- Physical Countermeasures
 - Active mesh
 - o Glue cell network
 - Voltage glitch detection
 - o Chip decap sensing
 - Thermal attack
 - o Memory fault detection
 - o False injection detection
 - Side channel protection, clock jitter, power balancing
 - o Redundant key registers
 - Puzzle routing
 - Secret zeroization
- Integrated PMU
 - Operation from single supply
- Software Development Kit
- Optional packages
 - 188BGA 8mm X 8mm for MCU+SE function
 - o 71 Ball WLCSP for limited function
 - o KGD
- Operational temperature
 - o -20C to 85C ambient



1 Description

Daric is a novel integrated general purpose Microcontoller Unit (MCU) and Secure Element (SE), all under a common umbrella of logical countermeasures (LCMs) and physical countermeasures (PCMs). The entire chip has the physical security of a typical SE, but unlike standalone SE chips, also has the computing power of a powerful general purpose MCU. By using novel RRAM and 22nm ULL technology, speed, power, memory size, and security are all markedly enhanced. Key Features include:

Integrated MCU and SE

- Integrating both functions on a single die reduces cost, power, and area, and enhances security.
- Shielded MCU can secure important functions outside of SE, such as user display and input, which otherwise are typically executed in a general purpose MCU outside of the shield of PCMs.
- Most advanced MCU in M-series (M7) with advanced features such as cache, TCM, floating point unit, AXI bus fabric.
- Alternate boot mode into RiscV system with MMU (separate SKU option).

Code and NV data are stored in Resistive RAM, with many advantages over legacy floating gate flash.

- Not readable by simple physical attack such as passive voltage contrast or electron microscopy.
- Long retention (does not leak charge continuously).
- Robust against magnetic fields and high energy particles.
- High memory density enabling larger code/data space than comparable MCUs.
- Integrated with small 22nm ULL process (which floating gate cannot be).

The advanced 22nm ULL process has many advantages in the context of secure MCU:

- Low cost, power, size
- High speed operation (800MHz)
- Higher memory sizes due to high NVM and SRAM density
- Small feature size is naturally more resistant to physical attack, FIB, probe, and inspection.
- Countermeasures are also more effective due to high feature density and lower emissions.

Advanced Cryptographic Architecture

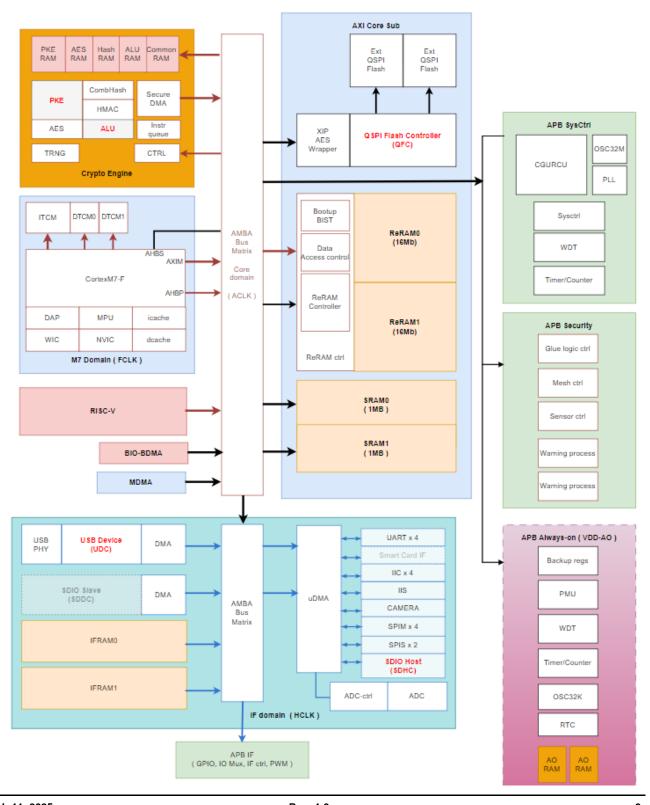
- Support for modern curves and functions with known performance and security advantages
- High throughput and low latency
- Atomic functions may be chained together directly in SE
 - Has the system isolation and simplicity of a direct hardware SE
- Alternately, the MCU may access atomic functions
 - Thus entire chip, including MCU, may be used as a flexible, physically shielded, "super SE" for cryptographic innovation

Open Development

- Supported with devkit and open development tools
- Open source strategy unlike typical banking/payment SE's



2 Block Diagram





3 Revision History

Rev.#	Date	Changes
.1	June 14, 2022	Initial draft
.2	Feb 11, 2023	Updated Crypto Features, RiscV Option
3	March 11, 2025	Overhauled to reflect latest architecture, features and performance

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